# **BAS40L, SBAS40L**

## **Schottky Barrier Diodes**

These Schottky barrier diodes are designed for high speed switching applications, circuit protection, and voltage clamping. Extremely low forward voltage reduces conduction loss. Miniature surface mount package is excellent for hand held and portable applications where space is limited.

#### **Features**

- S Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q101 Qualified and PPAP Capable
- These Devices are Pb–Free, Halogen Free/BFR Free and are RoHS Compliant

#### **MAXIMUM RATINGS**

Rating	Symbol	Value	Unit
Reverse Voltage	$V_{R}$	40	V
Forward Power Dissipation @ T <sub>A</sub> = 25°C Derate above 25°C	P <sub>F</sub>	225 1.8	mW mW/°C
Operating Junction and Storage Temperature Range	T <sub>J,</sub> T <sub>stg</sub>	-55 to +150	°C
Forward Continuous Current	I <sub>F</sub>	120	mA
Forward Surge Current $t \le 1 \text{ s}$ $t \le 10 \text{ ms}$	I <sub>FSM</sub>	200 600	mA
Thermal Resistance (Note 1) Junction-to-Ambient (Note 2)	$R_{ heta JA}$	508 311	°C/W

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

- 1. FR-4 @ minimum pad.
- 2. FR-4 @ 1.0 x 1.0 in pad.



#### ON Semiconductor®

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# 40 VOLTS SCHOTTKY BARRIER DIODES



SOT-23 (TO-236) CASE 318 STYLE 8



#### **MARKING DIAGRAM**



B1 = Specific Device Code

M = Date Code\*

= Pb-Free Package

(Note: Microdot may be in either location)

#### **ORDERING INFORMATION**

Device	Package	Shipping <sup>†</sup>
BAS40LT1G,	SOT-23	3,000 /
SBAS40LT1G	(Pb-Free)	Tape & Reel
BAS40LT3G,	SOT-23	10,000 /
SBAS40LT3G	(Pb-Free)	Tape & Reel

<sup>†</sup>For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

<sup>\*</sup>Date Code orientation and/or overbar may vary depending upon manufacturing location.

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#### **ELECTRICAL CHARACTERISTICS** (T<sub>A</sub> = 25°C unless otherwise noted)

Characteristic	Symbol	Min	Max	Unit
Reverse Breakdown Voltage $(I_R = 10 \mu A)$	V <sub>(BR)R</sub>	40	-	V
Total Capacitance (V <sub>R</sub> = 1.0 V, f = 1.0 MHz)	СТ	-	5.0	pF
Reverse Leakage $(V_R = 25 \text{ V})$	I <sub>R</sub>	-	1.0	μAdc
Forward Voltage (I <sub>F</sub> = 1.0 mAdc)	V <sub>F</sub>	-	380	mVdc
Forward Voltage (I <sub>F</sub> = 10 mAdc)	V <sub>F</sub>	-	500	mVdc
Forward Voltage (I <sub>F</sub> = 40 mAdc)	V <sub>F</sub>	-	1.0	Vdc

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

#### **TYPICAL CHARACTERISTICS**

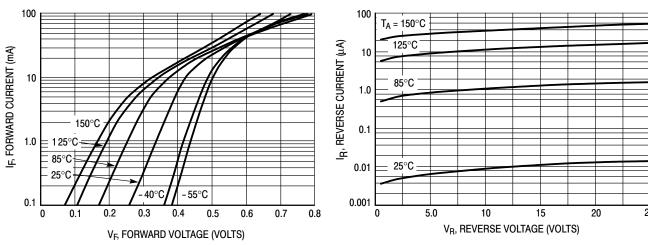


Figure 1. Typical Forward Voltage

Figure 2. Reverse Current versus Reverse Voltage

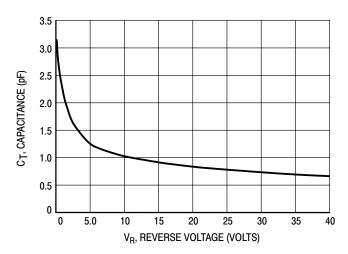
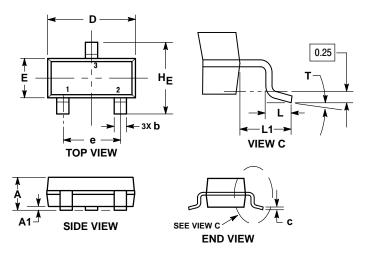


Figure 3. Typical Capacitance

#### BAS40L, SBAS40L

#### PACKAGE DIMENSIONS

#### SOT-23 (TO-236) CASE 318-08 **ISSUE AR**



- TES:
  DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
  CONTROLLING DIMENSION: MILLIMETERS.
  MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH.
  MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF
- THE BASE MATERIAL.

  DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH,
  PROTRUSIONS, OR GATE BURRS.

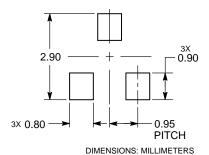
	MILLIMETERS			INCHES		
DIM	MIN	NOM	MAX	MIN	NOM	MAX
Α	0.89	1.00	1.11	0.035	0.039	0.044
A1	0.01	0.06	0.10	0.000	0.002	0.004
b	0.37	0.44	0.50	0.015	0.017	0.020
С	0.08	0.14	0.20	0.003	0.006	0.008
D	2.80	2.90	3.04	0.110	0.114	0.120
E	1.20	1.30	1.40	0.047	0.051	0.055
е	1.78	1.90	2.04	0.070	0.075	0.080
L	0.30	0.43	0.55	0.012	0.017	0.022
L1	0.35	0.54	0.69	0.014	0.021	0.027
HE	2.10	2.40	2.64	0.083	0.094	0.104
Т	0°		10°	0°		10°

#### STYLE 8:

ANODE

- NO CONNECTION
- CATHODE

#### **RECOMMENDED** SOLDERING FOOTPRINT\*



\*For additional information on our Pb-Free strategy and soldering

details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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